

Attorney [redacted] et No. 5051-575

2823/4  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Franzon et al.  
Serial No.: 09/997,586  
Filed: November 28, 2001  
For: BURIED SOLDER BUMPS FOR AC-COUPLED MICROELECTRONIC  
INTERCONNECT

Group Art Unit: 6227  
Examiner: Hsien Ming Lee  
Confirmation No.: 6227

February 19, 2003

Commissioner for Patents  
Washington, DC 20231

Sir:

Transmitted herewith is a PRELIMINARY AMENDMENT in the above-identified patent application.

- ☐ Applicant claims small entity status. See 37 CFR §1.27.  
☐ No additional fee is required.  
☐ Other:

The fee has been calculated as shown below:

(COL. 1)		(COL. 2)	(COL. 3)	SMALL ENTITY		OTHER THAN A SMALL ENTITY	
	Claims Remaining After Amendment	Highest Number Previously Paid For	Present Extra	RATE	ADDIT. FEE	OR RATE	ADDIT. FEE
Total	* 89 -	** 77	= 12	x 09=	\$	x 18=	\$ 216.00
Indep	* 7 -	*** 7	= 0	x 42=	\$	x 84=	\$
<input type="checkbox"/> FIRST PRESENTATION OF MULTIPLE DEP. CLAIM				+140=	\$	+280=	\$
				Total Add. Fee \$		OR Total	\$ 216.00

- \* If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.  
\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.  
\*\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space. The "Highest Number Previously Paid For" (Total or Independent) is the highest number found from the equivalent box in Col. 1 of a prior Amendment or the number of claims originally filed.

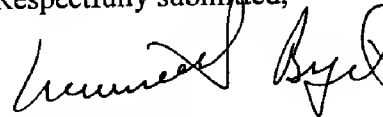
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Page 2

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- ☐ Please charge my Deposit Account No. 50-0220 in the amount of \$ .
- ☒ A check in the amount \$216.00 to cover the additional fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0220.
- ☒ Any additional filing fees required under 37 C.F.R. § 1.16 for the presentation of extra claims.
- ☒ Any patent application processing fees under 37 C.F.R. § 1.17.

Respectfully submitted,



Mitchell S. Bigel  
Registration No. 29,614  
Attorney of Record

**Customer Number:**

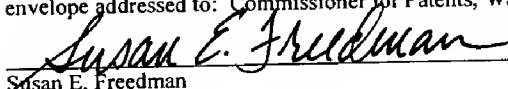


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PATENT TRADEMARK OFFICE

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on February 19, 2003.



Susan E. Freedman

Date of Signature: February 19, 2003



Attorney Docket No. 5051-575

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PRELIMINARY AMENDMENT

Sir:

Please enter the following Preliminary Amendment before examining the present application.

In the Claims:

Please add the following new Claims 78-89:

78. (New) A microelectronic package according to Claim 1 wherein the first microelectronic substrate comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package, and wherein the second microelectronic substrate also comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package.

79. (New) A microelectronic package according to Claim 19 wherein the microelectronic substrate comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package.

80. (New) A microelectronic package according to Claim 32 wherein the microelectronic substrate comprises one of an integrated circuit, a second level microelectronic package, a mating connector substrate or a third level microelectronic package.

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